

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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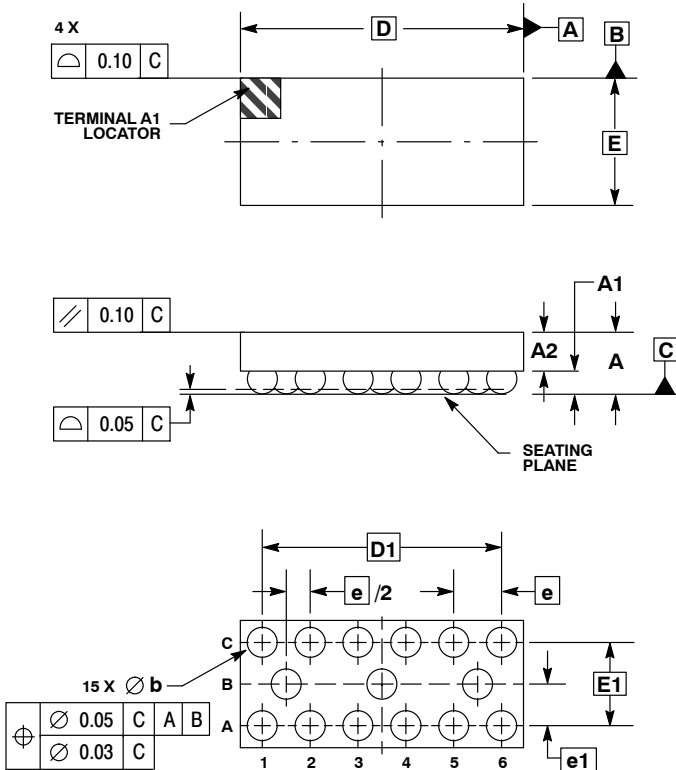


15 PIN FLIPCHIP CSP CASE 499D-01 ISSUE O

DATE 18-OCT-2002



SCALE 4:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	2.960 BSC	
E	1.330 BSC	
b	0.290	0.340
e	0.500 BSC	
e1	0.435 BSC	
D1	2.500 BSC	
E1	0.870 BSC	

GENERIC DEVICE MARKING



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DESCRIPTION:	15 PIN FLIPCHIP CSP	PAGE 1 OF 1

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